

EK-TM4C1294XL-BOOST-DLPTRF7970ABP Firmware Development Package

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Texas Instruments 108 Wild Basin, Suite 350 Austin, TX 78746 www.ti.com/tiva-c







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1 Introduction

The Texas Instruments® Tiva™ EK-TM4C1294XL-BOOST-DLPTRF7970ABP evaluation board (Tiva C Series TM4C1294 Connected LaunchPad) is a low cost platform that can be used for software development and prototyping a hardware design. A variety of BoosterPacks are available to quickly extend the LaunchPad's features.

The EK-TM4C1294XL includes a Tiva ARM® Cortex[™]-M4-based microcontroller and the following features:

- TivaTM TM4C1294NCPDT microcontroller
- Ethernet connector
- USB OTG connector
- 2 user buttons
- 4 User LEDs
- 2 BoosterPack XL sites
- On-board In-Circuit Debug Interface (ICDI)
- Power supply option from USB ICDI connection, USB OTG connection or external power connection
- Shunt jumper for microcontroller current consumption measurement

This document describes the example applications that are provided for the EK-TM4C1294XL when paired with the BOOST-DLPTRF7970ABP BoosterPack. This BoosterPack provides the TRF7970ABP NFC device. The example utilize the TivaWare[™] for C Series NFC Library to operate as a P2P device.

2 Example Applications

The example applications show how to utilize features of this evaluation board. Examples are included to show how to use many of the general features of the Tiva microcontroller, as well as the feature that are unique to this evaluation board.

A number of drivers are provided to make it easier to use the features of this board. These drivers also contain low-level code that make use of the TivaWare peripheral driver library and utilities.

There is an IAR workspace file (ek-tm4c1294x1-boost-dlptrf7970abp.eww) that contains the peripheral driver library project, along with all of the board example projects, in a single, easy-to-use workspace for use with Embedded Workbench

There is a Keil multi-project workspace file (ek-tm4c1294x1-boost-dlptrf7970abp.mpw) that contains the peripheral driver library project, along with all of the board example projects, in a single, easy-to-use workspace for use with uVision.

All of these examples reside in the examples/boards/ek-tm4c1294xl-boost-dlptrf7970abp subdirectory of the firmware development package source distribution.

2.1 NFC P2P Demo (nfc_p2p_demo)

This example application demonstrates the operation of the Tiva C Series evaluation kit with the TRF7970ABP BoosterPack as a NFC P2P device.

The application supports reading and writing Text, URI, and SmartPoster Tags. The application gets a raw message buffer from the TRF79x0 stack, decodes the information to recognized tag types, then re-encodes the data to a buffer to be sent back out. Pressing switch SW1 sends a URI message with a link to the Tiva C series Launchpad website. Pressing switch SW2 echo's back the last tag recieved. If no tag has been recieved then this button does nothing. Full debug information is given across the UART0 channel to aid in NFC P2P development.

This application assumes the TRF7970ABP is connected to the boosterpack 2 headers on the development kit. To use the boosterpack 1 headers you will need to toggle the TRF79X0_USE_BOOSTERPACK_2 define in trf79x0_hw.h and recompile the application.

For more information on NFC please see the full NFC specification list at http://www.nfc-forum.org/specs/spec_list/.

3 Buttons Driver

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3.1 Introduction

The buttons driver provides functions to make it easy to use the push buttons on this evaluation board. The driver provides a function to initialize all the hardware required for the buttons, and features for debouncing and querying the button state.

This driver is located in examples/boards/ek-tm4c1294xl-boost-dlptrf7970abp/drivers, with buttons.c containing the source code and buttons.h containing the API declarations for use by applications.

3.2 API Functions

Functions

- void ButtonsInit (void)
- uint8_t ButtonsPoll (uint8_t *pui8Delta, uint8_t *pui8RawState)

3.2.1 Function Documentation

3.2.1.1 ButtonsInit

Initializes the GPIO pins used by the board pushbuttons.

Prototype:

void
ButtonsInit(void)

Description:

This function must be called during application initialization to configure the GPIO pins to which the pushbuttons are attached. It enables the port used by the buttons and configures each button GPIO as an input with a weak pull-up.

Returns:

None.

3.2.1.2 ButtonsPoll

Polls the current state of the buttons and determines which have changed.

Prototype:

Parameters:

pui8Delta points to a character that will be written to indicate which button states changed since the last time this function was called. This value is derived from the debounced state of the buttons.

pui8RawState points to a location where the raw button state will be stored.

Description:

This function should be called periodically by the application to poll the pushbuttons. It determines both the current debounced state of the buttons and also which buttons have changed state since the last time the function was called.

In order for button debouncing to work properly, this function should be called at a regular interval, even if the state of the buttons is not needed that often.

If button debouncing is not required, the the caller can pass a pointer for the *pui8RawState* parameter in order to get the raw state of the buttons. The value returned in *pui8RawState* will be a bit mask where a 1 indicates the buttons is pressed.

Returns:

Returns the current debounced state of the buttons where a 1 in the button ID's position indicates that the button is pressed and a 0 indicates that it is released.

3.3 Programming Example

The following example shows how to use the buttons driver to initialize the buttons, debounce and read the buttons state.

4 Pinout Module

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4.1 Introduction

The pinout module is a common function for configuring the device pins for use by example applications. The pins are configured into the most common usage; it is possible that some of the pins might need to be reconfigured in order to support more specialized usage.

This driver is located in examples/boards/ek-tm4c1294xl-boost-dlptrf7970abp/drivers, with pinout.c containing the source code and pinout.h containing the API declarations for use by applications.

4.2 API Functions

Functions

- void LEDRead (uint32 t *pui32LEDValue)
- void LEDWrite (uint32_t ui32LEDMask, uint32_t ui32LEDValue)
- void PinoutSet (bool bEthernet, bool bUSB)

4.2.1 Function Documentation

4.2.1.1 LEDRead

This function reads the state to the LED bank.

Prototype:

```
void
LEDRead(uint32_t *pui32LEDValue)
```

Parameters:

pui32LEDValue is a pointer to where the LED value will be stored.

Description:

This function reads the state of the CLP LEDs and stores that state information into the variable pointed to by pui32LEDValue.

Returns:

None.

4.2.1.2 LEDWrite

This function writes a state to the LED bank.

Prototype:

Parameters:

ui32LEDMask is a bit mask for which GPIO should be changed by this call.
ui32LEDValue is the new value to be applied to the LEDs after the ui32LEDMask is applied.

Description:

The first parameter acts as a mask. Only bits in the mask that are set will correspond to LEDs that may change. LEDs with a mask that is not set will not change. This works the same as GPIOPinWrite. After applying the mask the setting for each unmasked LED is written to the corresponding LED port pin via GPIOPinWrite.

Returns:

None.

4.2.1.3 PinoutSet

Configures the device pins for the standard usages on the EK-TM4C1294XL.

Prototype:

Parameters:

bEthernet is a boolean used to determine function of Ethernet pins. If true Ethernet pins are configured as Ethernet LEDs. If false GPIO are available for application use.

bUSB is a boolean used to determine function of USB pins. If true USB pins are configured for USB use. If false then USB pins are available for application use as GPIO.

Description:

This function enables the GPIO modules and configures the device pins for the default, standard usages on the EK-TM4C1294XL. Applications that require alternate configurations of the device pins can either not call this function and take full responsibility for configuring all the device pins, or can reconfigure the required device pins after calling this function.

Returns:

None.

4.3 Programming Example

The following example shows how to configure the device pins.

```
//
// The pinout example.
//
void
PinoutExample(void)
{
    //
    // Configure the device pins.
    // First argument determines whether the Ethernet pins will be configured
    // in networking mode for this application.
    // Second argument determines whether the USB pins will be configured for
    // USB mode for this application.
    //
    PinoutSet(true, false);
}
```

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